

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Surface mounting technology –
Part 3: Standard method for the specification of components for through-hole
reflow (THR) soldering**

**Technique du montage en surface –
Partie 3: Méthode normalisée relative à la spécification des composants pour
le brasage par refusion à trous traversants (THR, Through Hole Reflow)**





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SURFACE MOUNTING TECHNOLOGY –**Part 3: Standard method for the specification of components for through-hole reflow (THR) soldering**

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This second edition cancels and replaces the first edition published in 2010. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) change position tolerance requirement (0,4 mm maximum to between 0,2 mm and 0,4 mm);
- b) introduce through-hole vacant method as a solder paste supply method.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1684/FDIS	91/1702/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

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